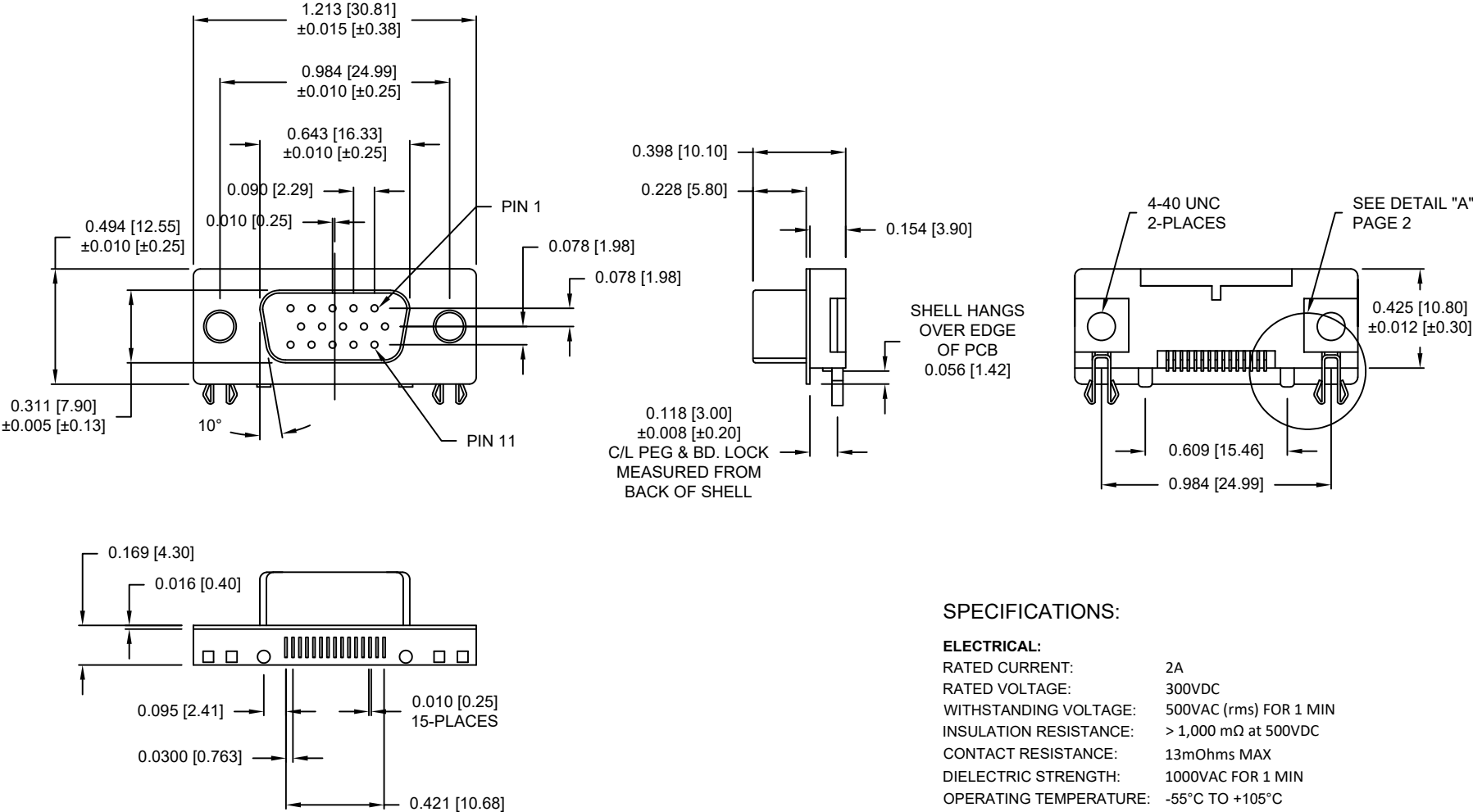




SPECIFICATIONS:

ELECTRICAL:	
RATED CURRENT:	2A
RATED VOLTAGE:	300VDC
WITHSTANDING VOLTAGE:	500VAC (rms) FOR 1 MIN
INSULATION RESISTANCE:	> 1,000 mΩ at 500VDC
CONTACT RESISTANCE:	13mOhms MAX
DIELECTRIC STRENGTH:	1000VAC FOR 1 MIN
OPERATING TEMPERATURE:	-55°C TO +105°C

MATERIALS:	
SHELL:	80μ" MIN NICKEL PLATED STEEL
BRACKET:	80μ" MIN TIN OVER 50μ" MIN NICKEL PLATED BRASS
INSULATOR:	NYLON 6T, UL 94V-0, BLACK
PROCESS TEMP:	260°C
INSULATOR:	PATONE #322C, COLOR=Pc99
CONTACT:	PHOSPHOR BRONZE 1μ" MIN GOLD FLASH MATING AREA 100μ" MIN TIN PLATED SOLDER AREA

Storage and Process Instructions:

For parts exposed to greater than 60% RH, it is recommended parts be baked at 125°C for 3-5 hours prior to SMT reflow process. If unsure of RH exposure, it is recommend to bake at the above temperature and time prior to SMT reflow process.

RoHS COMPLIANT



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DRAWN:
C. SMITH

DATE:
03/27/2009

UNITS = inch [mm]

DO NOT SCALE FROM DRAWING

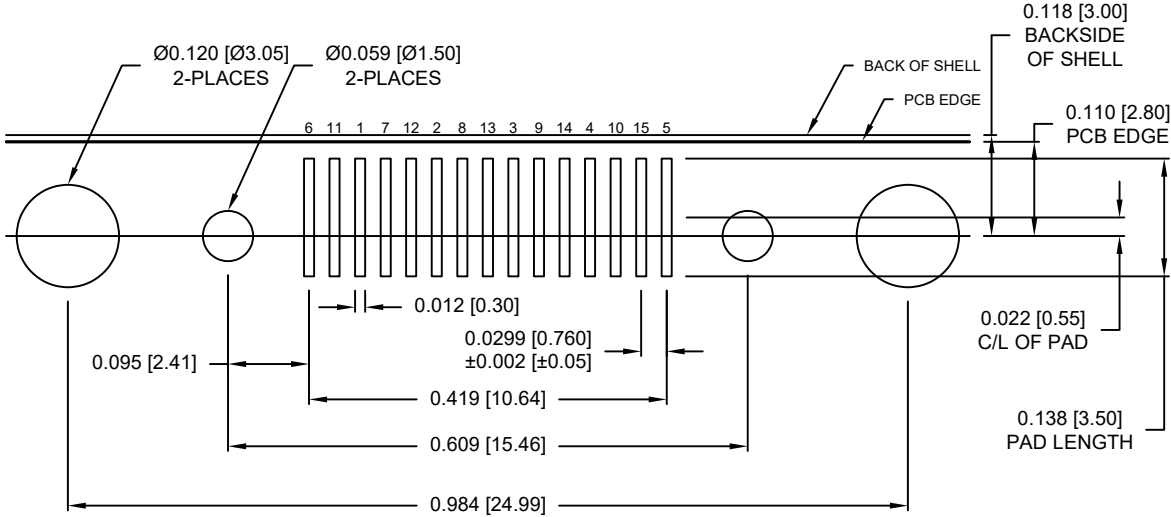
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SCALE:
NTS

SHEET 1 OF 2

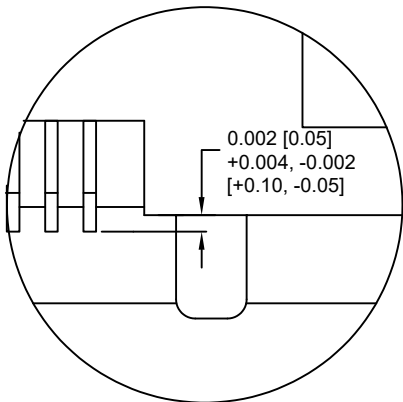
REV
16

DWG NO. 200-015-263R001



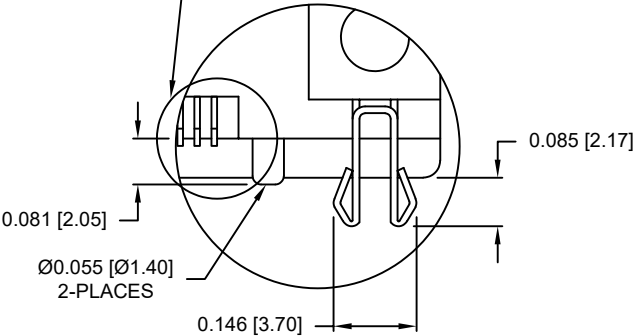
RECOMMENDED PCB LAYOUT

CONTACT ARRANGEMENT
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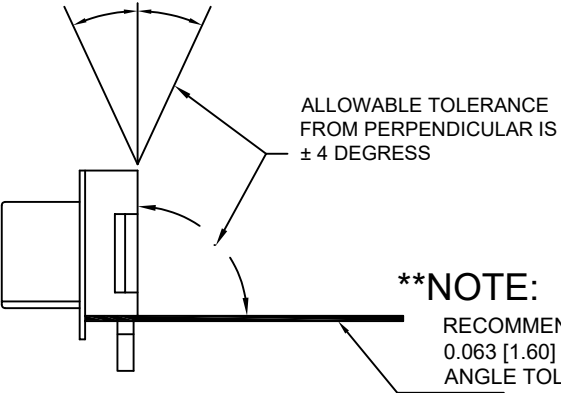


DETAIL "B"
CONTACT COPLANARITY

SEE DETAIL "B"
FOR CONTACT
COPLANARITY



DETAIL "A"



****NOTE:**
RECOMMENDED PCB THICKNESS IS
0.063 [1.60] ± 0.002 [0.05] TO MAINTAIN
ANGLE TOLERANCE

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SCALE: NTS	SHEET 2 OF 2	REV 16
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